

SPECIFICATION FOR LCD MODULE

MODULE NO: AFK240320A1-2.4INTM REVISION NO: V02

Customer's Approval:

| | SIGNATURE | DATE |
|---------------------------|-----------|------|
| PREPARED BY (RD ENGINEER) | | |
| CHECKED BY | | |
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Contents

| 1 | Introduction | 4 |
|----|------------------------------------|----|
| 2 | General specification | 5 |
| 3 | Mechanical drawing | 6 |
| 4 | Block diagram | 7 |
| 5 | Interface Pin Function | 8 |
| 6 | Absolute maximum ratings | 10 |
| 7 | Electrical characteristics | 10 |
| 8 | Optical characteristics | 11 |
| 9 | Timing characteristics | 14 |
| 10 | Standard Specification | 17 |
| 11 | Specification of Quality Assurance | 19 |
| 12 | Handling Precaution | 27 |
| 13 | Packing method | 27 |

1. Introduction

1.1 Scope of application

This specification applies to the positive type TFT transmissive dot matrix LCD module.

LCD resolution: Dots 240xRGBx320.

As to basic specification of the driver IC, refer to the IC (ILI9341V) specification and data sheet.

1.2 Structure:

Module Structure: TFT Panel+Polarizer+IC+FPC+BL; Full 262K/65K Color 2.4 inch TFT Panel; One bare chip with gold bump (COG) TECH; Support 80 MCU 8/9/16/18-bit bus interface I; White LED back light;

1.3 TFT features:

Transmissive Type LCD, normally black; 240 dot-source and 320 dot-gate outputs; All viewing direction;

1.4 Applications:

Mobile phone PSP PDA GPS Etc...

2. General specification

| ITEM | Standard value | UNIT | | |
|--------------------|------------------------------|------|--|--|
| Display Mode | Transmissive, Normally black | | | |
| Driver Mothod | TFT Active matrix | | | |
| Number of Dots | 240 (RGB) *320 | Dots | | |
| Pixel Arrangement | RGB Vertical Stripe | | | |
| Active Area | 36. 72*48. 96 | mm | | |
| Viewing Direction | A11 | | | |
| Driver IC | ILI9341V | | | |
| Module Size(W*H*T) | 42. 72*60. 4*2. 2 | mm | | |
| Approx. Weight | TBD | g | | |
| Back Light | 4-Dies White LED series | | | |
| System interface | I80 MCU 8/9/16/18-bit | | | |

3. Mechanical Drawing



4. BLOCK DIAGRAM



5. Interface Pin Function

| Pin No. | Symbol | Description |
|------------|--------|--|
| 1 | GND | Power ground |
| 2 | IMO | Select the MCU interface mode |
| 3 | IM1 | Select the MCU interface mode |
| 4 | FMARK | Tearing effect output pin to synchronize MPU to frame writing, activated by S/W command. When this pin is not activated, this pin is low. If not used, open this pin. |
| 5 | NC | No connection |
| 6 | DB17 | |
| 7 | DB16 | |
| 8 | DB15 | |
| 9 | DB14 | |
| 10 | DB13 | |
| 11 | DB12 | Data bus. |
| 12 | DB11 | |
| 13 | DB10 | |
| 14 | DB9 | |
| 15 | DB8 | |
| 16 | IOVCC | Power supply for interface logic circuits (1.8V/2.8V). |
| 17 | DB7 | |
| 18 | DB6 | |
| 19 | DB5 | |
| 20 | DB4 | - Data bus. |
| 21 | DB3 | Data bus. |
| 22 | DB2 | |
| 23 | DB1 | |
| 24 | DBO | |
| 25 | /CS | Chip selection pin Low enable; High disable. |
| 26 | RS | This pin is used to select "Data or Command" in the parallel interface. When RS= 1, data is selected. When RS= 0, command is selected. |
| 27 | WR | Serves as a write signal and writes data at the rising edge. |
| 28 | RD | Serves as a read signal and MCU read data at the rising edge. |
| 29 | /RESET | This signal will reset the device and must be applied to properly initialize the chip. Signal is active low. |

| 30 | VCI | Power voltage(2.8V) |
|----|------|--------------------------|
| 31 | GND | Power ground |
| 32 | LED+ | Anode of LED backlight |
| 33 | GND | Power ground |
| 34 | LED- | Cathode of LED backlight |
| 35 | GND | Power ground |

Note: Select the MCU interface mode

| IM1 | IMO | MCU-Interface Mode | DB Pin in use |
|-----|-----|-------------------------------|---------------|
| 0 | 0 | 80 MCU 8-bit bus interface I | DB[7:0] |
| 0 | 1 | 80 MCU 16-bit bus interface I | DB[15:0] |
| 1 | 0 | 80 MCU 9-bit bus interface I | DB[8:0] |
| 1 | 1 | 80 MCU 18-bit bus interface I | DB[17:0] |

6. ABSOLUTE MAXIMUM RATINGS

| Parameter | Symbol | Min | Max | Unit |
|---------------------------|-----------------|------|---------|------|
| Supply voltage for logic | IOVCC | -0.3 | 4.6 | V |
| Supply voltage for Analog | VCI | -0.3 | 4.6 | V |
| Input voltage | VIN | -0.3 | VCI+0.3 | V |
| Supply current (One LED) | ILED | | 30 | mA |
| Operating temperature | T _{OP} | -20 | +70 | °°C |
| Storage temperature | T _{st} | -30 | +80 | °°C |

7. ELECTRICAL CHARACTERISTICS

For IC

| Item | Symbol | Min | Тур | Max | Unit | Applicable terminal |
|---------------------------|-----------------------------|--------|-----|--------|------|------------------------|
| Supply voltage for logic | IOVCC | 1.65 | 2.8 | 3.3 | V | |
| Supply voltage for Analog | VCI | 2.5 | 2.8 | 3.3 | V | |
| Input voltogo | VIL | VSS | _ | 0.3VCI | V | |
| Input voltage | VIH | 0.7VCI | _ | VCI | V | |
| Input leakage current | $\mathrm{I}_{\mathrm{LKG}}$ | -0.1 | | +0.1 | μA | |

For backlight

| Item | Symbol | Min | Тур | Max | Unit | Condition |
|-------------------|------------------|------|-------|------|-------|-----------|
| Supply Current | Ι | | 20 | | mA | |
| Forward Voltage | V_{led} | 12.0 | 12.8 | 13.6 | V | I=20mA |
| Power Consumption | Р | | 256 | | mW | |
| Life Time | | | 50000 | | Hours | Note |

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

| 8. | OPTICAL | CHARACTERISTICS |
|----|---------|-----------------|
|----|---------|-----------------|

| ттем | r | CVMDOI | CONDITIONS | SPEC | IFICAT | IONS | | NOTE |
|-------------|-------|------------------|--------------|-------|--------|-------|----------|------|
| ITEM | | SYMBOL | CONDITIONS | MIN. | TYP. | MAX | UNIT | NOTE |
| Brightness | | В | | 300 | | _ | Cd/m^2 | |
| Contrast Ra | tio | CR | | | 800 | | | |
| Response Ti | me | Tr+Tf | | | 35 | 45 | ms | |
| | Red | XR | | | | | | |
| | | Yr | Viewing | | | | | |
| CIE | Green | Xg | normal angle | | | | | |
| Color | | YG | | | | | | |
| coordinate | Blue | Хв | | | | | | |
| coordinate | | Yв | | | | | | |
| | White | Xw | | 0.260 | 0.280 | 0.300 | | |
| | | Yw | | 0.289 | 0.309 | 0.329 | | |
| | Hor. | θ_{X^+} | | | 80 | | | |
| Viewing | | $\theta_{_{X-}}$ | Center | | 80 | | Der | |
| Angle | Ver. | $	heta_{_{Y+}}$ | CR>=10 | | 80 | | Deg. | |
| | | $	heta_{Y-}$ | | | 80 | | | |
| Uniformity | Un | | | 80 | | | % | |

Note 1 : Definition of Viewing Angle vande v:



Note 2: Definition of contrast ratio CR: $CR = \frac{\text{Brightness of non-selected dots (white)}}{\text{Brightness of selected dots (black)}}$





The brightness test equipment setup 20mA Field=2° (As measuring "black" image, field=2° is the best testing condition)



Note 4:

23



9. Timing characteristics





| Signal | Symbol | Parameter | min | max | Unit | Description |
|---------------------------------|--------|------------------------------------|-----|-------------|------|---------------------|
| DCX | tast | Address setup time | 0 | | ns | |
| DUX | taht | Address hold time (Write/Read) | 0 | - | ns | |
| | tchw | CSX "H" pulse width | 0 | - | ns | |
| | tcs | Chip Select setup time (Write) | 15 | | ns | |
| CSX | trcs | Chip Select setup time (Read ID) | 45 | | ns | |
| | trcsfm | Chip Select setup time (Read FM) | 355 | - | ns | |
| | tcsf | Chip Select Wait time (Write/Read) | 10 | | ns | |
| | twc | Write cycle | 66 | 12 | ns | |
| WRX | twrh | Write Control pulse H duration | 15 | | ns | |
| | twrl | Write Control pulse L duration | 15 | 18 | ns | |
| | trcfm | Read Cycle (FM) | 450 | - | ns | |
| RDX (FM) | trdhfm | Read Control H duration (FM) | 90 | (B | ns | |
| | trdlfm | Read Control L duration (FM) | 355 | | ns | |
| | trc | Read cycle (ID) | 160 | 19 4 | ns | |
| RDX (ID) | trdh | Read Control pulse H duration | 90 | 112 | ns | |
| | trdl | Read Control pulse L duration | 45 | - | ns | |
| | tdst | Write data setup time | 10 | - | ns | |
| D[17:0], D[15:0], D[8:0], | tdht | Write data hold time | 10 | . 4 | ns | |
| | trat | Read access time | #61 | 40 | ns | For maximum CL=30pF |
| | tratfm | Read access time | - | 340 | ns | For minimum CL=8pF |
| D[7:0] | trod | Read output disable time | 20 | 80 | ns | |

Note: Ta=-30 to 70°C, IOVCC=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V



CS timings:



Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

Write to read or read to write timings:



Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

9.2 Reset Timing



- Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

| RESX Pulse | Action |
|----------------------|----------------|
| Shorter than 5us | Reset Rejected |
| Longer than 10us | Reset |
| Between 5us and 10us | Reset starts |

- Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.
- Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



Note 5: When Reset applied during Sleep In Mode.

- Note 6: When Reset applied during Sleep Out Mode.
- Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

10. Standard Specification for Reliability :

| No | Item | Description |
|----|-------------------------------|--|
| 01 | High temperature operation | The sample should be allowed to stand at $70 ^{\circ}\mathrm{C}$ for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 02 | Low temperature operation | The sample should be allowed to stand at -20 °C for 240 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 03 | High temperature storage | The sample should be allowed to stand at $80 ^{\circ}$ C for 240 hours under no- load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 04 | Low temperature storage | The sample should be allowed to stand at -30°C for 240 hours under no- load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours. |
| 05 | Moisture storage | The sample should be allowed to stand at 60° C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours. |
| 06 | Thermal shock storage | The sample should be allowed to stand the following 10 cycles : -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle. |
| 07 | Packing vibration | Frequency range : 10Hz \sim 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction. |
| 08 | Packing drop test | According to ISTA 1A 2001. |
| 09 | 09 Electrical Static | Air: ± 4 KV 150pF/330 Ω 5 times |
| | Discharge | Contact: ± 2 KV 150pF/330 Ω 5 time |

10 - 1. Standard Specifications for Reliability of LCD Module

*Sample size for each test item is 3^{5} pcs

10 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 12.2, Standard specifications for Reliability have been executed in order to ensure stability.

| No | Item | Test Model | In section Criteria |
|----|------------------------|------------------------|--|
| 01 | Current Consumption | Refer To Specification | The current consumption should conform to the product specification. |
| 02 | Contrast | Refer To Specification | After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests. |
| 03 | Appearance | Visual inspection | Defect free. |

10-3. MTBF

| MTBF | Functions, performance, appearance, etc. shall be free from remarkable deterioration within10,000 hours under ordinary operating and storage conditions room temperature $(25 \pm 5 ^{\circ}{\rm C})$, normal humidity $(50 \pm 10\%$ RH), and in area not exposed to direct sun light. |
|------|--|
|------|--|

11. Specification of Quality Assurance:

11-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by Orient Display.

11-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to MIL-STD105E.General Inspection Level II take a single time.
- (ii) The defects classify of AQL as following:
 - Major defect: AQL = 0.65
 - Minor defect: AQL = 2.5
 - Total defects: AQL = 2.5
- 11-3. Non- conforming Analysis & Deal With Manners

a. Non- conforming Analysis:

- (i) Purchaser should supply the detail data of non- conforming sample and the non- conforming.
- (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
- (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.

(ii) Both supplier and customer should analyze the reason and discuss the disposition of nonconforming when the reason of nonconforming is not sure.

11-4. Agreement items

Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

11-5. Standard of The Product Appearance Test

a. Manner of appearance test:

(i) The test must be under 20W \times 2 or 40W fluorescent light, and the distance of view must be at 30 $\pm\,5{\rm cm}.$

- (ii) When test the model of transmissive product must add the reflective plate.
- (iii)The test direction is base on around $10\,^\circ\,$ of vertical line.
- (iiii)Temperature: 25 ± 5 °C Humidity: 60 ± 10 %RH



(iv) Definition of area:



A. Area: Viewing area.

B. Area: Out of viewing area. (Outside viewing area)

- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.

c. Standard of inspection: (Unit: mm)

11-6. Inspection specification

| NO | Item | Criterion | | | |
|----|---|--|------|--|--|
| 01 | Electrical Testing | 1 Missing vertical, horizontal segment, segment contrast defect. 2 Missing character, dot or icon. 3 Display malfunction. 4 No function or no display. 5 Current consumption exceeds product specifications. 6 LCD viewing angle defect. 7 Mixed product types. 8 Flicker | | | |
| 02 | Black or White spots or Bright spots or Color spots on LCD (Display only) | 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. | 2. 5 | | |
| | LCD and Touch | 3.1 Round type: As following drawing $\Phi = (X+Y) / 2$ $\underbrace{Size(mm)}_{\Phi \leq 0.10} Acceptable Q' ty}_{\Phi \leq 0.10}$ $\underbrace{\Phi \leq 0.10}_{Accept no dense}_{\Phi \leq 0.20} 2$ $\underbrace{0.20 \langle \Phi \leq 0.25 \rangle}_{0.25 \langle \Phi \leq 0.30 \rangle}_{1}$ $\underbrace{0.30 \langle \Phi \rangle}_{\Phi \leq 0.30 \rangle}_{1}$ | 2. 5 | | |
| 03 | Panel black spots, white spots, contamination (non - display) | 3.2 Line type: (As following drawing) Length(m Width(mm) Acceptable Q'ty m) W≦0.02 Accept no dense L≦3.0 0.02 <w≦0.05 2<br="">L≦2.5 0.03<w≦0.08 2<br=""> 0.08<w rejection<br="">* Densely spaced: No more than two lines within 3mm.</w></w≦0.08></w≦0.05> | 2. 5 | | |

| NO | Item | | Criterion | | AQL |
|----|----------------------|---|---|--|--------------------|
| 04 | Polarizer bubbles | If bubbles are visible, judge using black spot specifications, not eas to find, must check in specify direction | $\Phi \leq 0.$ | 20 Accept n ≤0.50 3 ≤1.00 2 Φ 0 | <u>o dense</u> 2.5 |
| 05 | Scratches | Follow NO.3 -2 Line Typ | pe. | | |
| 06 | Chipped glass | <pre>L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel su:</pre> | <pre>: Glass thickness a: h : rface and crack betwe : Chip width dot over viewing area Not exceed 1/3k : Chip width dot over viewing area Not exceed 1/3k</pre> | en panels: x: Chip length $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$ $x \le 1/8a$ | |

| NO | Item | Criterion | AQL |
|----|---------------------|---|-------------|
| N0 | Item Glass crack | CriterionSymbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length | AQL 2. 5 |
| | | Specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7. 2. 3 Substrate protuberance and internal crack y: width x: length | |
| | | $y \le 1/3L$ $X \le a$ | |
| | | | |

| NO | Item | Criterion | AQL |
|----|-----------------------|--|--|
| 08 | Cracked glass | The LCD with extensive crack is not acceptable. | 2.5 |
| 09 | Backlight elements | 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. | 2.5 2.5 0.65 |
| 10 | Bezel | Bezel must comply with product specifications. | 2.5 |
| 11 | РСВ、СОВ | 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. | 2.5 2.5 2.5 2.5 0.65 0.65 |
| 12 | FPC | 12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function, we judge accept. | 2.5 2.5 |
| 13 | Soldering | 13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC. | 2.5 0.65 |

| Item | Criterion | AQL |
|---|---|---|
| Item Touch Panel Chipped glass | Criterion Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels: Image: Chip thickness y: Chip width x: State x = 1/8a O Unit: mm O If there are 2 or more chips, x is the total length of each chip 14.1.2 Corner crack: Image: Chip thickness y: Chip width x: Chip length z: Chip thickness y: Chip width x: Chip thickness y: Chip width x: Chip length z = 1/2 k and not over yiewing area x = 1/8a | AQL 2.5 |
| | ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip | |
| | Touch Panel Chipped | Touch Panel Chipped glass Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length 14. 1 General glass chip: 14. 1. 1 Chip on panel surface and crack between panels: Image: Touch Panel Chipped glass Image: Touch Panel Chipped 0 If there are 2 or more chips, x is the total length of each chip 14. 1. 2 Corner crack: Image: Touch Panel Chipped glass Image: Touch Panel Chipped glass Image: Chip thickness 0 Unit: mm 0 If there are 2 or more chips, x is the total length of each chip 14. 1. 2 Corner crack: Image: Touch Panel Chipped glass Image: Touch Panel Chipped glass Image: Chip thickness 0 Unit: mm 0 If there are 2 or more chips, x is the total length of each chip 14. 1. 2 Corner crack: Image: Thickness Image: |

| NO | Item | Criterion | AQL |
|----|---|--|----------------------------------|
| 15 | Touch Panel(Fish eye、dent and bubble on film) | SIZE (mm)Acceptable Q' ty $\Phi \leq 0.2$ Accept no dense $0.2 \langle D \leq 0.4$ 5 $0.4 \langle D \geq 0.5$ 2 $0.5 \langle D$ 0 | 2.5 |
| 16 | Touch Panel Newton ring | Newton ring dimension $\leqq 1/2$ touch panel area and not affect font and line distortion($\leqq 2.5\%)$, it is acceptable. | 2. 5 |
| 17 | Touch Panel Linearity | Less than 2.5% is acceptable. | 2.5 |
| 18 | LCD Ripple | Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g | 2.5 |
| 19 | General appearance | 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. | 0. 65 0. 65 0. 65 0. 65 |

12. Handling Precaution:

$12\mathchar`-1$ Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.

• The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

12-2 Storage

- Store in an ambient temperature of 25 ± 10 °C, and in a relative humidity of 50 ± 10 %RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

11-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10℃ and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

13 Packing method

----TBD